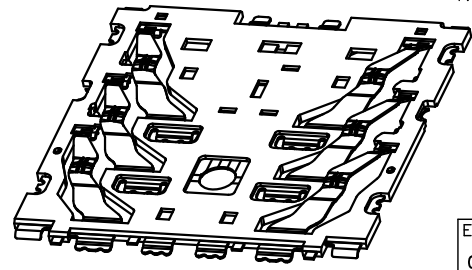


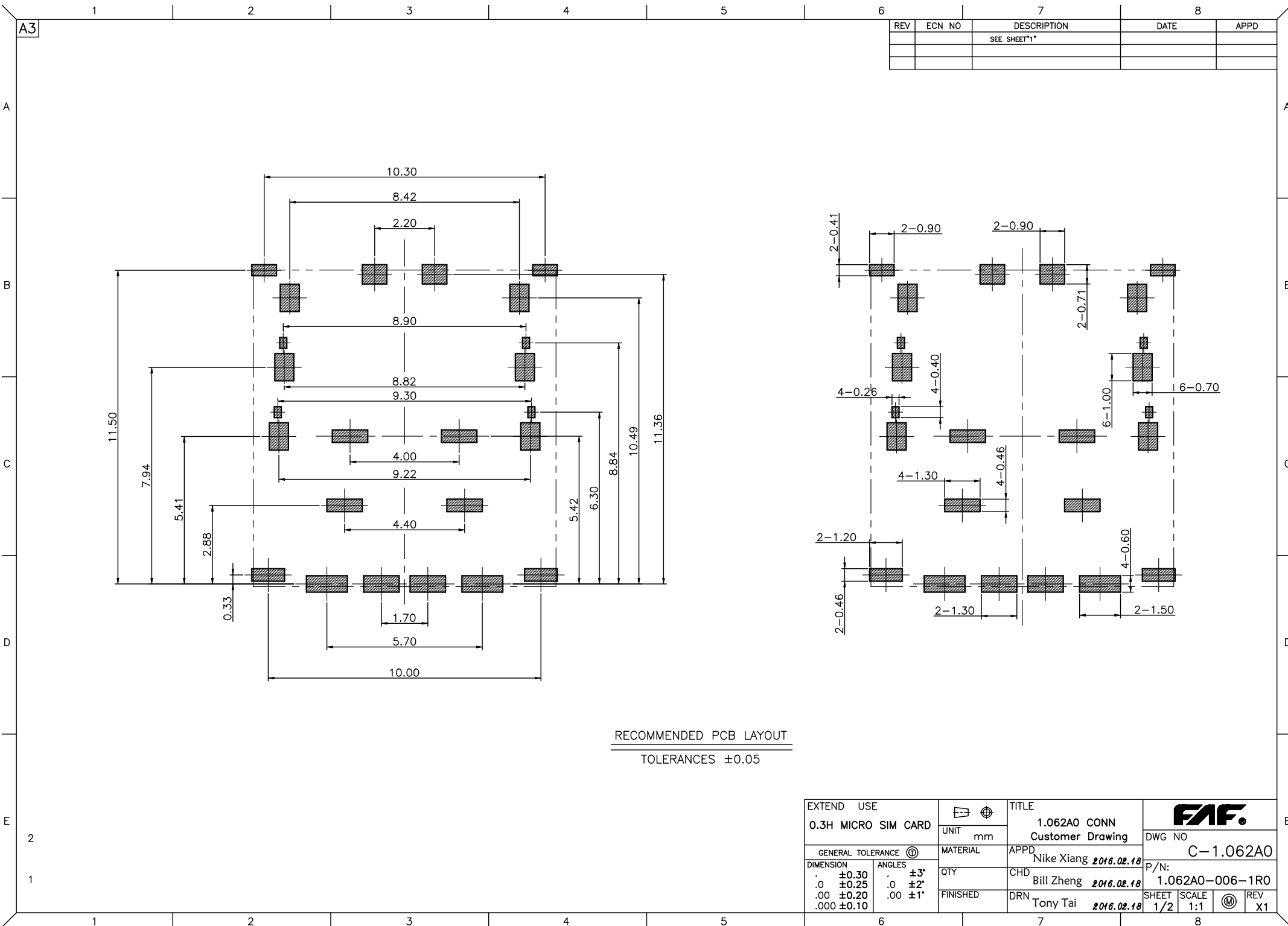
REV	ECN NO	DESCRIPTION	DATE	APPD
X1		INITIAL RELEASE	2016.02.18	

NOTE:

- MATERIALS:
 - HOUSING: THERMOPLASTIC, LCP S475, UL94 V-0, COLOR: BLACK;
 - TERMINAL: COPPER ALLOY C17200-190 XHM/C17200-190 XHMB, T=0.06±0.01;
- FINISH:
 - TERMINAL: 15u" Min. GOLD PLATING ON CONTACT AREA, GOLD FLASH PLATED ON SOLDERING TAIL, 50u" Min. NICKEL UNDER PLATING OVERALL;



EXTEND USE	TITLE			
0.3H MICRO SIM CARD	UNIT	1.062A0 CONN	Customer Drawing	
	mm	APPD	DWG NO	
GENERAL TOLERANCE (0)	MATERIAL	APPD	C-1.062A0	
DIMENSION	ANGLES	QTY	P/N:	
±0.30	±3°	CHD	1.062A0-006-1R0	
.0 ±0.25	.0 ±2°	FINISHED	SHEET	SCALE
.00 ±0.20	.00 ±1°	DRN	1/2	1:1
.000 ±0.10			REV	X1



REV	ECN NO	DESCRIPTION	DATE	APPD
		SEE SHEET*1*		

RECOMMENDED PCB LAYOUT
TOLERANCES ±0.05

EXTEND USE				TITLE			
0.3H MICRO SIM CARD		UNIT mm		1.062A0 CONN		DWG NO	
GENERAL TOLERANCE Ⓢ		MATERIAL		APPD		C-1.062A0	
DIMENSION		ANGLES		CHD		P/N:	
. ±0.30	. ±3°	QTY		Bill Zheng 2016.02.18		1.062A0-006-1R0	
.0 ±0.25	.0 ±2°	FINISHED		DRN		SHEET SCALE	
.00 ±0.20	.00 ±1°	Tony Tai 2016.02.18		1/2		1:1	
.000 ±0.10						REV X1	